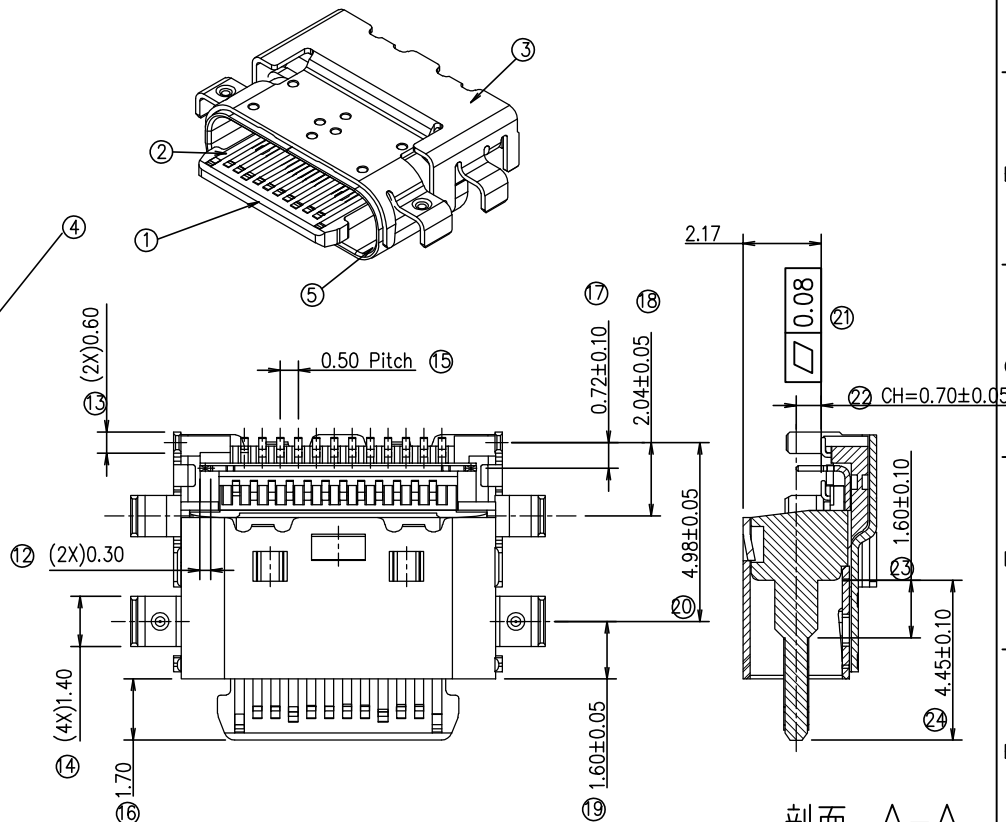
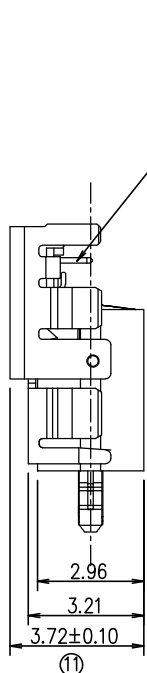
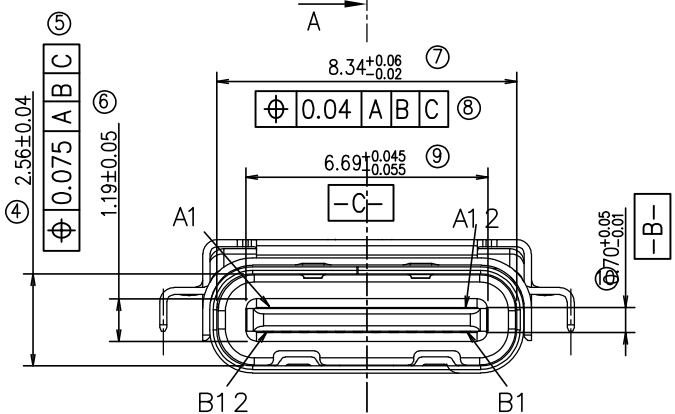
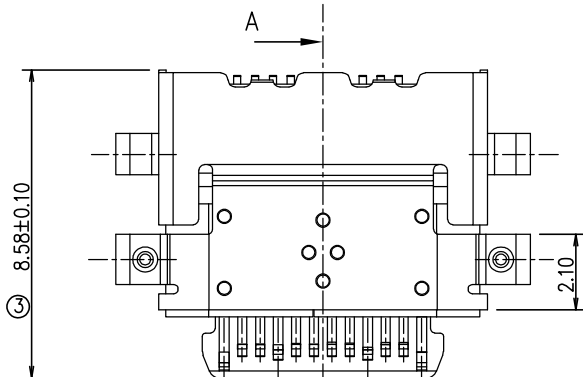
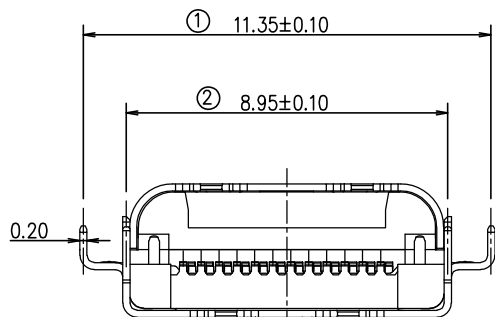


成品图

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
X0			NEW	2020/12/26	LML



剖面 A-A

5	INTERNAL SHELL	SUS304-1/2H	SOLDERABLE NI 50u" Min. OVER ALL	1
4	MID-PLATE	SUS301-H	SOLDER AREA: G/F; NI 50u"Min. OVER ALL	1
3	SHELL	SUS304-1/2H	SOLDERABLE NI 50u" Min. OVER ALL	1
2	CONTACT	C7035-TM06	CONTACT AREA: Au 30u" Min.; SOLDER AREA: G/F; NI 50u"~150u". OVER ALL.	12
1	HOUSING	PA46, HFX31S	BLACK, UL 94V-0	1
ITEM	DEFINITION	MATERIAL	FINISH	Q'TY

东莞市溪榜电子有限公司
DONG GUAN XI BANG ELECTRONICS CO., LTD.

DRAW NO.		DATE	2016/12/26	MATERIAL:SEE NOTES	DRAW NAME:
DESIGN:	LML	FINISH:SEE NOTES		FILE:	Type C 沉板CH=0.7 (Mi8 SE)
CHECK:					MODEL:
REVIEW:					
APPROVED		REV. X1	SCALE N/A	UNIT: mm	SHEET: 1/1

DIM	TOL	DIM	DEG
X.	±0.15	X'.	±3°
X.X	±0.10	X.X'	±2°
X.XX	±0.05	X.XX'	±1°
X.XXX	±0.02	X.XXX'	±0.5°

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
X0			NEW	2021/12/26	LML



1. 电气性能:

- 1-1. 额定电流: 3A;
- 1-2. 接触阻抗: 40mΩ最大;
- 1-3. IR test: 500VDC, 0.1S, 50M Ω;
- 1-4. Hi pot test: 300VAC, 0.1S, 0.5mA;

2. 机械性能:

- 2-1. 插入力: 5~20N;
- 2-2. 拔出力: 8~20N(未插过), 6~20N(10000 次耐久测试后);
- 2-3. 测试速度: 200±50 次/小时, 测试 10000 次;

3. 标示 “▼” 尺寸必须记录实际检验数据, 标示 “ ” 的尺寸重点确认;

4. 本产品使用物料及制程须符合“QW-Q-043”文件对环境管理物质及RoHS2.0&HF要求;

DIM	TOL	DIM	DEG
X.	±0.15	X°.	±3°
X.X	±0.10	X.X°	±2°
X.XX	±0.05	X.XX°	±1°
X.XXX	±0.02	X.XXX°	±0.5°

Pin	Signal Name	Description	Mating Sequence	Pin	Signal Name	Description	Mating Sequence
A1	GND	Ground return	First	B12	GND	Ground return	First
A2	SSTxp1	Positive half of first SuperSpeed TX differential pair	Second	B11	SSRxp1	Positive half of first SuperSpeed RX differential pair	Second
A3	SSTXn1	Negative half of first SuperSpeed TX differential pair	Second	B10	SSRXn1	Negative half of first SuperSpeed RX differential pair	Second
A4	VBUS	Bus Power	First	B9	VBUS	Bus Power	First
A5	CC1	Configuration Channel	Second	B8	SBU2	Sideband Use	Second
A6	Dp1	Positive half of the USB2.0 differential pair—Position 1	Second	B7	Dn2	Negative half of the USB2.0 differential pair—Position 2	Second
A7	Dn1	Negative half of the USB2.0 differential pair—Position 1	Second	B6	Dp2	Positive half of the USB2.0 differential pair—Position 2	Second
A8	SBU1	Sideband Use	Second	B5	CC2	Configuration Channel	Second
A9	VBUS	Bus Power	First	B4	VBUS	Bus Power	First
A10	SSRXn2	Negative half of second SuperSpeed RX differential pair	Second	B3	SSTXn2	Negative half of second SuperSpeed TX differential pair	Second
A11	SSRxp2	Positive half of second SuperSpeed RX differential pair	Second	B2	SSTxp2	Positive half of second SuperSpeed TX differential pair	Second
A12	GND	Ground return	First	B1	GND	Ground return	First

XG 东莞市溪榜电子有限公司
DONG GUAN XI BANG ELECTRONICS CO., LTD.

DRAW NO.		DATE	MATERIAL:SEE NOTES		DRAW NAME:		
DESIGN:	LML	2016/12/26	FINISH:SEE NOTES		Type C 沉板CH=0.7 (Mi8 SE)		
CHECK:			FILE:		MODEL:		
REVIEW:					UNIT:	SHEET:	
APPROVED			REV. X1	SCALE N/A	mm	1/1	